REMARKS

Amendments

The amendment to the Specification merely inserts the prior application information. Claim 1 is amended to recited limitations of claims 3-5; claim 11 is amended to recited the suggested structural language. These amendments introduce no new matter.

35USC112, second paragraph

Claims 1-31: "wire bonding capillary". A wire bonding capillary is a definite term of art; see Specification, p.9, lines 5-17. Wire bonding capillaries are well known in the semiconductor manufacturing art, are the subject of numerous publications and patents (see e.g. US Pat Nos. 3,894,671; 4,877,173; 5,082,154; 5,558,270; 5,662,261) and are commercially available from a number of sources (e.g. Micro-Swiss of Kulicke & Soffa Industries, Inc., Willow Grove PA; Gaiser Tool Company, Ventura, CA; Small Precision Tools, Petaluma, CA, etc.). See also the disclosures and claims of US Pat Nos. 6,158,647; 6,065,663; 6,006,977; 5,996,877; 5,971,248; 5,944,249; 5,934,543; 5,927,587; 5,662,261; 5,559,054; 5,031,821; 4,974,767; 4,911,350; 4,513,190; etc.

Claim 11: "the system prints". This phrase has been replaced with the suggested structural language.

35USC102(b)

Claim 1. JP04-69943. Our claims require a wire bonding capillary "containing a liquid". We believe that one skilled in the art would not construe the end of the copper wire shown in the cited art to be a "liquid" - if it was a liquid, it would act like a liquid and rise up the bore by capillary action. In any event, we do not intend our claims to encompass capillaries containing molten metal. The recited liquid of the amended claims excludes any liquid metals, yet encompasses essentially any other liquid: aqueous liquids, liquids comprising an organic solvent, polar or nonpolar, and liquids comprising a nonpolar solvent.

35USC103(a)

Claims 1-10, 12-23, 26-27 and 29-31. Little et al., US Pat. No. 6,024,925.

Claims 1-23 and 26-31. Feygin, US Pat. No. 5,957,167

Claims 24-25. Feygin (supra) and Thomas, US Pat. No. 5,544,535.

Our claims require the use of a wire bonding capillary for fluid handling. Wire bonding capillaries are used to make electrical connections in microelectronics. Never before has anyone suggested these devices could be used in fluid delivery. The cited art teaches conventional fluid delivery capillaries. None of the cited art teaches or suggests any use of wire bonding capillaries, as the term is understood in the art.

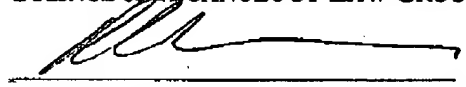
Double Patenting

Clams 2 and 12. A terminal disclaimer over US Application No. 09/884,506 is enclosed.

The Examiner is invited to call the undersigned if she would like to amend the claims to clarify the foregoing or seeks further clarification of the claim language.

We petition for and authorize charging our Deposit Account No.19-0750 all necessary extensions of time. The Commissioner is authorized to charge any fees or credit any overcharges relating to this communication to our Dep. Acct. No.19-0750 (order IN-0012-1).

Respectfully submitted,
SCIENCE & TECHNOLOGY LAW GROUP



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encl. Terminal Disclaimer (1p).

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